

IN THE SPECIFICATION:

Please insert the following paragraph below the title of the invention:

This application is a division of Application No. 10/014,398, filed December 14, 2001, now allowed.

Please amend the paragraph beginning at page 6, line 20, as follows:

For example, in the case of a wiring formed on a glass substrate is made thick, a crack may be formed in the glass substrate in a region where the end of the wiring is in contact with the substrate (such crack being hereinafter called as an end crack). Also a crack may be generated in the glass substrate in a direction parallel to the longitudinal direction of the wiring (such crack being hereinafter called a side crack).

Please amend the paragraph beginning at page 7, line 19, as follows:

Such situations will be explained further with reference to Figs. 15A to 15D, schematically showing the drawbacks resulting from the wiring substrate of the conventional technology. Figs. 15A to 15D schematically show a wiring formed on a substrate, wherein Fig. 15A is a plan view, Fig. 15B is an enlarged perspective view, seen from the rear side, of a circled portion 15B in Fig. 15A, Fig. 15C is a magnified look-through view, seen from the rear side, of encircled portion 15C in Fig. 15A, and Fig. 15D is a cross-sectional view along a line 15D-15D in Fig. 15A.

Please amend the paragraph beginning at page 18, line 17, as follows:

Also, when the wiring is seen from above in planar manner, the notch 12 may have a linear shape such as a continuous straight line, a broken line or a curved line, or an individually independent shape (such as a pattern of small circles). Also the direction of the notch 12 may or may not be along the longitudinal direction of the substrate. Furthermore, the cross-sectional shape (in vertical cross section) of the notch 12 may be a V shape of an acute angle, a U shape or an undulating shape.

Please amend the paragraph beginning at page 25, line 19, as follows:

The example 1 has a configuration, among the aforementioned embodiments, identical with that shown in Figs. 1A to 1G, wherein ~~shown~~ a notch 12, a wiring 11 and a substrate 13 are shown.

Please amend the paragraph beginning at page 31, line 5, as follows:

In the screen printing method, since the paste is discharged from the pattern of the plate, the actually printed ink becomes continuous by the ink flow at the printing and drying despite of the notch-forming slit being as wide as 50 μm , thereby generating surface irregularities on the wiring pattern to form, through the baking process, the upper wiring 17 with notch as shown in Fig. 5B.